

SMAJ Plastic-Encapsulate Diodes

Super Fast Recovery Rectifier Diode

Features

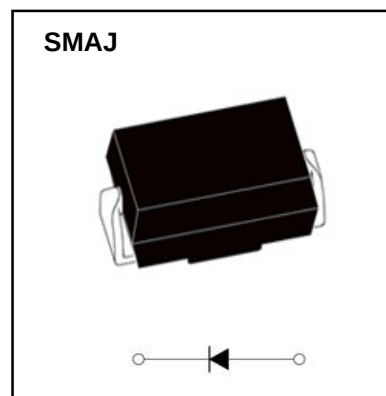
- I_o 1A
- V_{RRM} 50V-600V
- High surge current capability
- Glass passivated chip
- Polarity: Color band denotes cathode

Applications

- Rectifier

Marking

- ER1X
- X : From A To J



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	ER1							
				A	B	C	D	E	G	H	J
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	150	200	300	400	500	600
Maximum RMS Voltage	V_{RMS}	V		35	70	105	140	210	280	350	420
Average Forward Current	$I_{F(AV)}$	A	60HZ Half-sine wave, Resistance load, $T_a=75^\circ\text{C}$	1.0							
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave ,1 cycle , $T_a=25^\circ\text{C}$	30							
Junction Temperature	T_J	$^\circ\text{C}$		-55~+125							
Storage Temperature	T_{STG}	$^\circ\text{C}$		-55 ~ +150							

Electrical Characteristics (T=25°C Unless otherwise specified)

Item	Symbol	Unit	Test Condition		ER1						
					A	B	C	D	E	G	H
Peak Forward Voltage	V _F	V	I _F =1.0A		0.95				1.25		1.70
Maximum reverse recovery time	t _{rr}	ns	I _F =0.5A,I _R =1.0A,I _{rr} =0.25A		35						
Peak Reverse Current	I _{RRM1}	μA	V _{RM} =V _{RRM}	T _a =25℃	5						
	T _a =100℃			100							
Thermal Resistance(Typical)	R _{θJ-A}	℃/W	Between junction and ambient		55 ¹⁾						
	R _{θJ-L}		Between junction and terminal		25 ¹⁾						
Typical junction capacitance	C _j	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C.		15						

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

Typical Characteristics

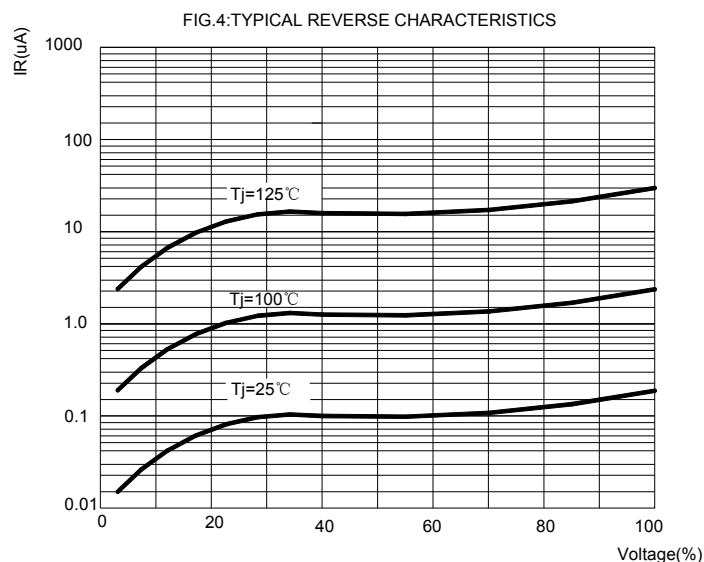
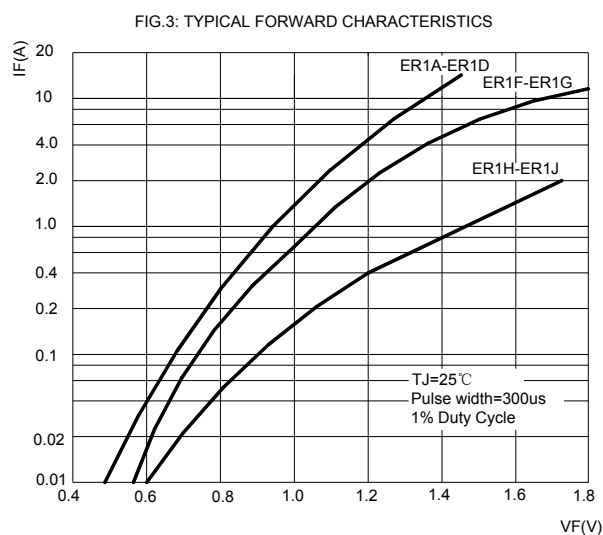
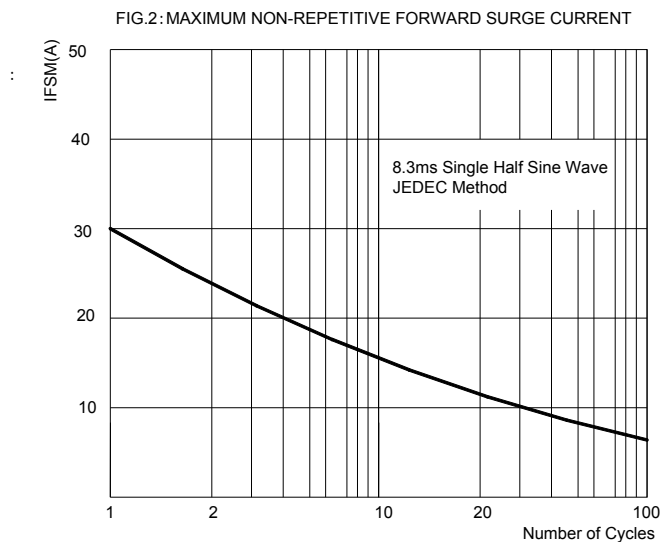
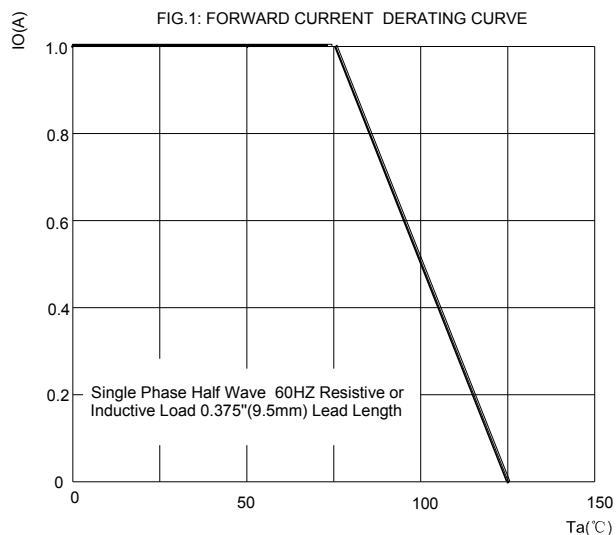
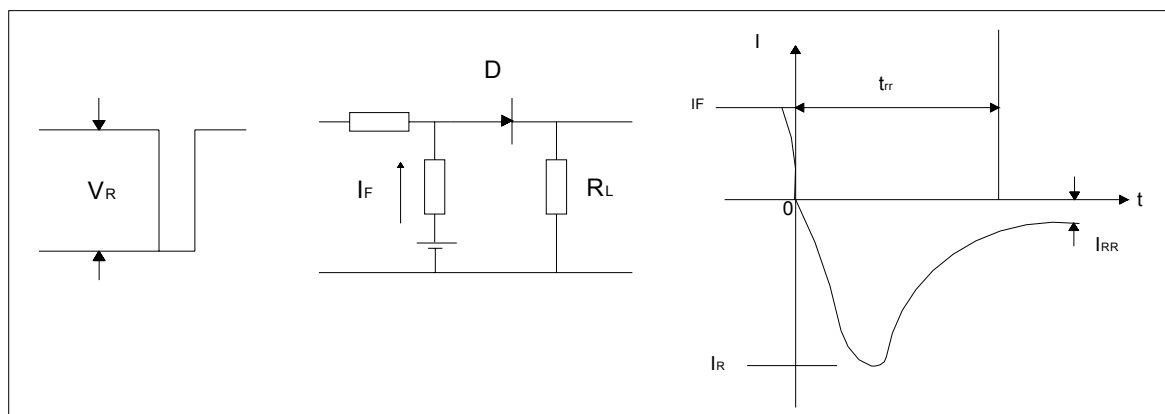
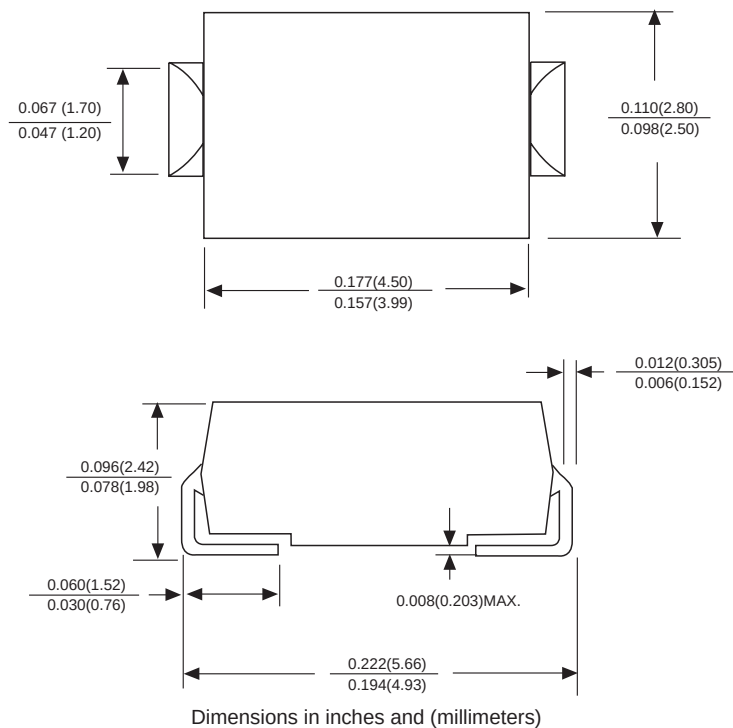


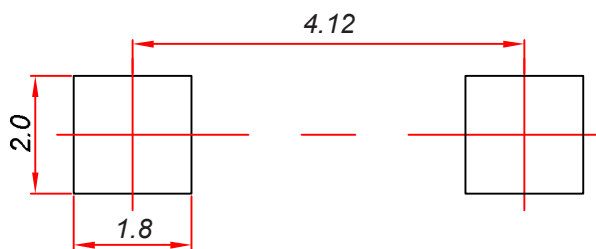
FIG.5: Diagram of circuit and Testing wave form of reverse recovery time



SMAJ Package Outline Dimensions



SMAJ Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

NOTICE

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Reel Taping Specifications For Surface Mount Devices–SMA

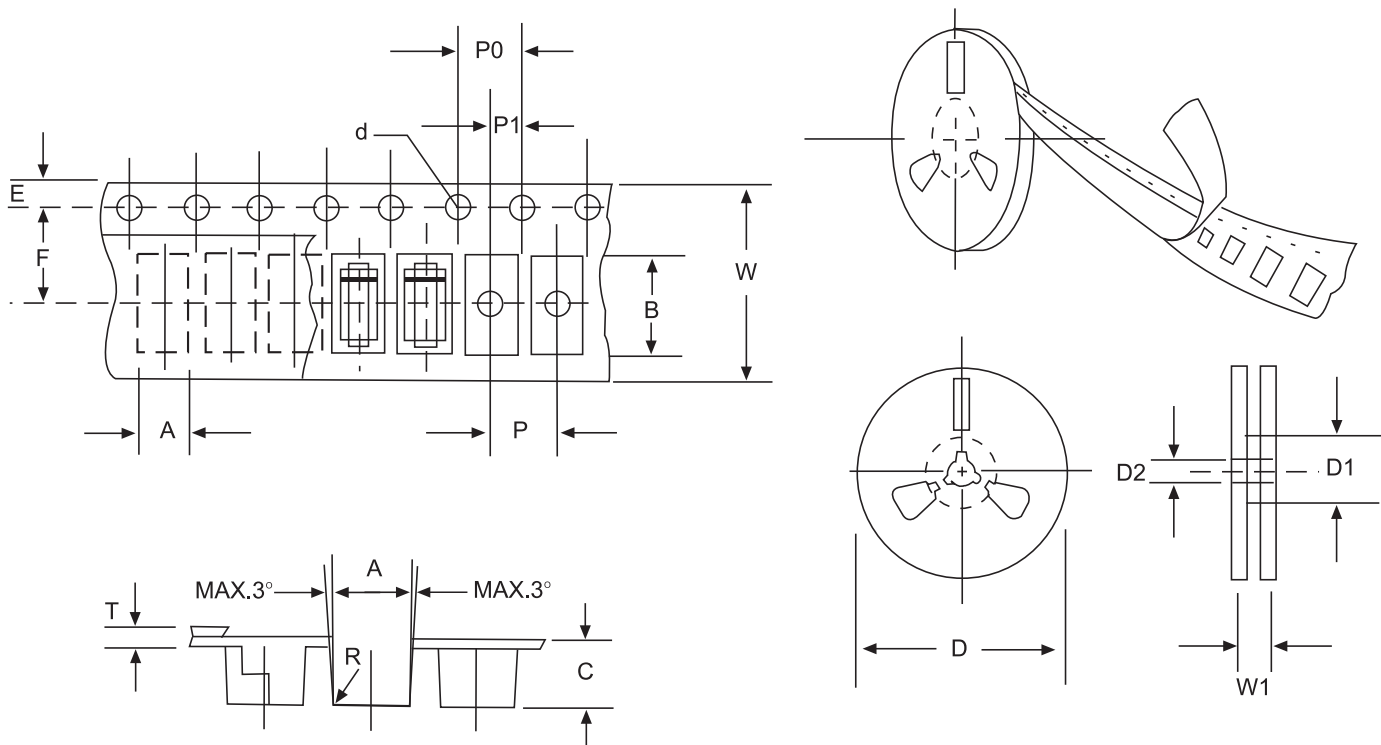


FIG:CONFIGURATION OF AXIAL TAPING

ITEM	SYMBOL	SMA mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.5±0.05(0.059±0.0002)
Reel outside diameter	D	330/178±2.0(13/7.0±0.79)
Reel inner diameter	D1	8.0±0.2(0.315±0.008)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.28±0.02(0.011 ±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.